PRINTED CIRCUIT BOARDS
INTERCONNECTION CARRIERS

Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h+ i
08	163	FR4	55	L10.70	P10	

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

08_163_FR4_55_L10.70_p10

Layers	in µ	Material	Build-Up	Assembly
Layer-1	55µ	Copper		B
	100µ	Prepreg	(100 µ PrePreg-Type: 2125)	B
	100µ	Prepreg		B
Layer-2	70µ	Copper		A1, B
	100µ	L-FR4		A1, B
Layer-3	70µ	Copper		A1, B
	100µ	Prepreg		B
	100µ	Prepreg		B
Layer-4	70µ	Copper		A2, B
	100µ	L-FR4		A2, B
Layer-5	70µ	Copper		A2, B
	100µ	Prepreg		B
	100µ	Prepreg		B
Layer-6	70µ	Copper		A3, B
	100µ	L-FR4		A3, B
Layer-7	70µ	Copper		A3, B
	100µ	Prepreg		B
	100µ	Prepreg		B
Layer-99	55µ	Copper		B

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